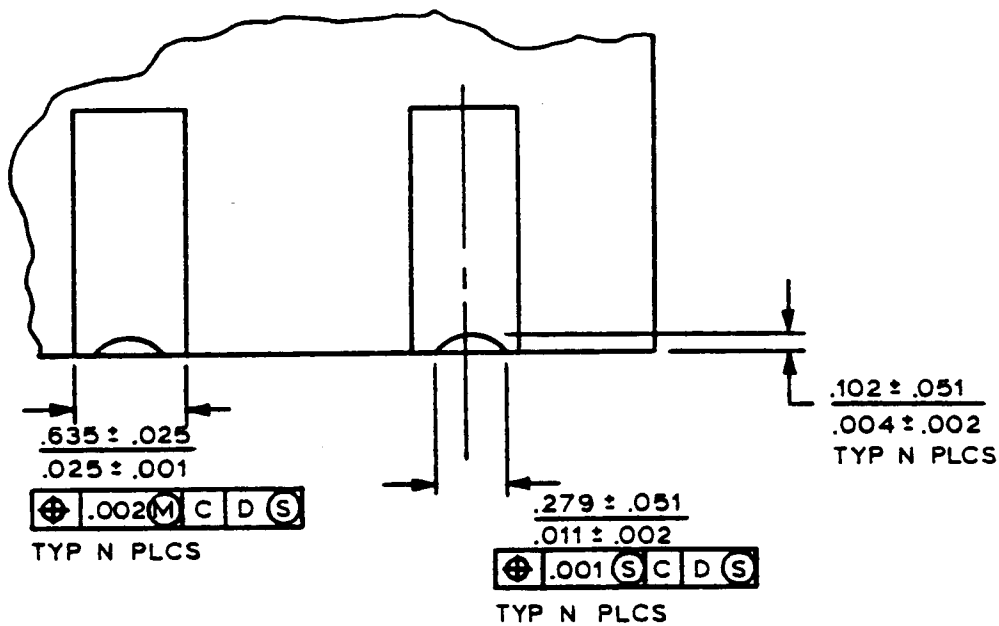


FIGURE 1: PRINCIPAL DIMENSIONS AND DATUMS

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BRITISH TELECOM
PATENTED PRODUCT



MILLIMETER
INCH

FIGURE 2: ENLARGED DETAIL A

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S Y M B O L	VARIATIONS ALL DIMENSIONS IN INCHES									
	AA		N O T E	AB		N O T E	AC		N O T E	
	MIN	MAX		MIN	MAX		MIN	MAX		
D	.189	.193		.342	.346		.386	.390		
D1	.150	BASIC	6	.300	BASIC	6	.350	BASIC	6	
D2	.181	REF		.334	REF		.378	REF		
E	.236	.240		.236	.240		.236	.240		
E1	.228	REF		.228	REF		.228	REF		
e	.050	BASIC	6	.050	BASIC	6	.050	BASIC	6	
M	4		6	7		6	8		6	
N	8		4	14		4	16		4	

SYM BOL	VARIATIONS ALL DIMENSIONS IN MILLIMETERS												
	AA		NOTE	AB		NOTE	AC		NOTE			NOTE	
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX		
D	4.801	4.902		8.687	8.788		9.804	9.906					
D1	3.810	BASIC	6	7.620	BASIC	6	8.890	BASIC	6				
D2	4.597	REF		8.484	REF		9.601	REF					
E	5.994	6.096		5.994	6.096		5.994	6.096					
E1	5.791	REF		5.791	REF		5.791	REF					
e	1.270	BASIC	6	1.270	BASIC	6	1.270	BASIC	6				
M	4		6	7		6	8		6				
N	8		4	14		4	16		4				
NOTE	1, 2, 3, 5			1, 2, 3, 5			1, 2, 3, 5						
REF	Item 11-221												
ISSUE	A												
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S Y M B O L	VARIATIONS ALL DIMENSIONS IN INCHES											N O T E
	AD		N O T E	AE		N O T E	AF		N O T E			
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX	
D	.502	.506		.604	.608		.706	.710				
D1	.450	BASIC	6	.550	BASIC	6	.650	BASIC	6			
D2	.494	REF		.596	REF		.715	REF				
E	.404	.408		.404	.408		.404	.408				
E1	.396	REF		.396	REF		.396	REF				
e	.050	BASIC	6	.050	BASIC	6	.050	BASIC	6			
M		10	6		12	6		14	6			
N		20	4		24	4		28	4			

SYM BOL	VARIATIONS ALL DIMENSIONS IN MILLIMETERS														
	AD		NOTE	AE		NOTE	AF		NOTE			NOTE			
	MIN	MAX		MIN	MAX		MIN	MAX		MIN	MAX				
D	12.751	12.852		15.342	15.443		17.932	18.034							
D1	11.430	BASIC	6	13.970	BASIC	6	16.510	BASIC	6						
D2	12.548	REF		15.138	REF		18.161	REF							
E	10.262	10.363		10.262	10.363		10.262	10.363							
E1	10.058	REF		10.058	REF		10.058	REF							
e	1.270	BASIC	6	1.270	BASIC	6	1.270	BASIC	6						
M	10		6	12		6	14		6						
N	20		4	24		4	28		4						
NOTE	1, 2, 3, 5			1, 2, 3, 5			1, 2, 3, 5								
REF	Item 11-222														
ISSUE	A														
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NOTES:

1. REFER TO APPLICABLE SYMBOL LIST.
2. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M 1982.
3. CONTROLLING DIMENSION: INCH.
4. N IS THE MAXIMUM QUANTITY OF TERMINAL POSITIONS.
5. PACKAGE SHALL BE FREE OF BURRS AND CORNERS SHALL BE SMOOTH.
6. M CENTERLINES SPACED AT e EQUAL TO D1 .
7. FEATURES FOR ELECTRICAL/OPTICAL ORIENTATION OR HANDLING PURPOSES MUST BE WITHIN THE AREA SHOWN.
8. THE LID DEFINED BY D2 AND E1 MUST BE LOCATED WITHIN DIMENSIONS D AND E.
9. THIS TECHNOLOGY WAS DEVELOPED IN THE U.K. FOR BRITISH TELECOMMUNICATIONS WHO HAVE PATENTS AND/OR PATENTS PENDING WORLD-WIDE. PRODUCTS EMPLOYING THE TECHNOLOGY ARE PRESENTLY MANUFACTURED BY TECTONIC PRODUCTS LTD. OF WOKINGHAM, U.K. THROUGH WHOM LICENSING IS AVAILABLE IN COMPLIANCE WITH PARAGRAPH 3.4 b) OF EIA ENGINEERING PUBLICATION EP-7-A.
10. APPLICATION NOTE: THESE DEVICES ARE INTENDED TO EXACTLY MATCH THE FOOTPRINTS OF REGISTERED AND STANDARDIZED SOIC OUTLINES.

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